

Date: November 2024
Rev: VI
No. of Components: Two
Mix Ratio by Weight: 10 : 1
Specific Gravity: Part A: 1.12 Part B: 1.02
Pot Life: 4 Hours
Shelf Life- Bulk: One year at room temperature
Shelf Life- Syringe: Six months at -40°C

Recommended Cure: 100°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
 80°C / 30 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- If product crystallizes in storage, place container in warm oven until crystallization disappears. Please refer to Tech Tip #7 on website.

Product Description: EPO-TEK® 343ND-LH (formerly R&D # 121-191-3) is a two component epoxy for fiber optic and semiconductor applications. Designed to balance a low temperature cure with reasonable pot life, EPO-TEK 343ND-LH maintains a long workable viscosity at room temperature and can be cured at 80°C in as little as 30 minutes. In addition, its high Tg is designed to provide high strength at elevated temperatures.

Typical Properties: Cure condition: Varies as required. Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:

* Color (before cure):	Part A: Light yellow	Part B: Light yellow
* Consistency:	Pourable liquid	
* Viscosity (23°C) @ 100 rpm:	2,000 – 4,000	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 80	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Shore D Hardness:	79	
Die Shear @ 23°C:	18	Kg
Degradation Temp:	422	°C
Weight Loss:		
	@ 200°C:	0.02 %
	@ 250°C:	0.16 %
	@ 300°C:	0.56 %
Suggested Operating Temperature:	< 350	°C (Intermittent)
Storage Modulus:	609,739	psi
Particle Size:	N/A	

OPTICAL PROPERTIES @ 23°C:

Spectral Transmission:	≥ 90% @ 800-1640	nm
Refractive Index (uncured):	1.5682 @ 589	nm

Epoxyes and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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